

ABSTRACT

10057237.042402

5 The present invention relates to a modular, prosthetic, implant assembly for replacing a shoulder or hip joint using a transosseous core approach. Typically, the main route for the transosseous core approach traverses through a more-accessible bone of the joint which can be aligned with a less-accessible bone of the joint in order to facilitate treatment of articular surfaces and/or other structures in the joint. A modular implant assembly is provided which can be passed through a relatively small bone hole and then assembled *in situ* partly in the bone hole and finished in the joint or wholly in the joint.

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